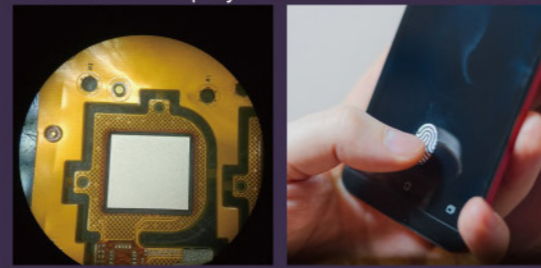


Optical signal identification module successful application, which Everwide lead in :

Bonding application on the fingerprint identification industry : Resistant against high/low temperature, moisture corrosion, salt spray corrosion.

- Product Feature :
1. Strong bonding strength for the stainless steel and glass housing materials with excellent insulation performance and excellent thermal conductivity.
 2. Our products can match up working parameters of the production lines. The resin is designed to be easier for dispensing, and it presents smooth and straight adhesive line to avoid unsmooth overflow after being laminated.
 3. The resin has excellent weather resistance, the adhesive can afford the conditions of -40°C*500hr, 85°C*500hr -40°C~85°C*30 cycles, 85°C*85%RH*168hr.
 4. Our products comply to the newest international environmental protection regulations, such as RoHS 2.0, Halogen Free, PFOA, PFOS, REACH, and etc.

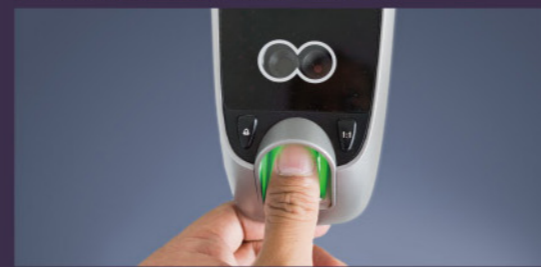
Product Model :
JD322 Series Epoxy resin
JD971 Series Epoxy resin



Encapsulation applications on the bio-medical sensor industry

- Product Feature :
1. The resin exhibits excellent transparency and anti-yellowing feature and it has great bonding strength to plastics, metals, ceramics and chips.
 2. The resin maintains certain balance level of cohesion between the substrates and the resin itself in order to mitigate the impact during the three-time dropping test.
 3. The weather resistance of this resin is excellent, which can afford the conditions of -40°C*240hr, 80°C*240hr, -40°C~85°C*240 cycles, 85°C*85%RH*240hr.
 4. The cured resin has excellent surface drying, it is required to be able to pass 24hr of sunscreen oil and alcohol soaking test.
 5. The resin have passed the cytotoxicity test.

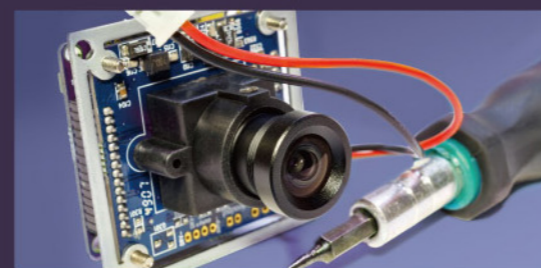
Product Model :
JD322 Series Low-temperature curing epoxy resin
FP614 Series Photo-curing adhesive



Applications on public area security monitoring industry

- Product Feature :
1. Our products comply to non-variable specifications at 80°C high temperature outdoor and it also comply to the environmental protection regulations.
 2. After photo-curing, the volumetric variation of the resin should be less than 3% to comply to the standard of low shrinkage.
 3. The bonding of the resin and the substrates should be rigid. Because the product should not expand and crack at the high temperature and it should lower the shrinking stress when it is cooled down.
 4. The resin has excellent chemical resistance, which can afford the erosion of oil. It can pass the high temperature, low temperature, high temperature and high humidity, and thermal cycling test.
 5. This product can satisfy the customer's requirements for waterproof. After sealing, it can reach the standard of IP68 or above after encapsulation and present a lustrous appearance.

Product Model :
FR395 Series Photo-curing adhesive
JD474 Series Photo-curing adhesive
JD912 Series Photo-curing adhesive
GM299 Series Photo-curing adhesive

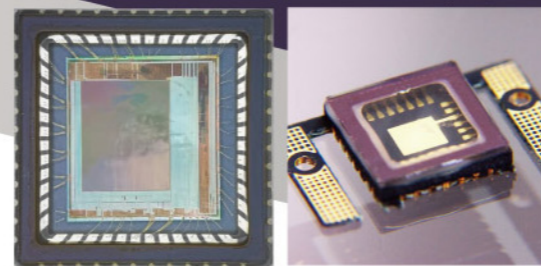


The sensor chip lens module industry successful application, which Everwide lead in :

Bonding for the PLCC and CLCC industry application

- Product Feature :
1. The resin exhibits excellent bonding strength on BT, FR4 substrates and optical glass. The product can pass three times of 260°C welding without peeling.
 2. Our products can match up working parameters of production line. The product is designed to be easier for dispensing, it presents smooth and straight resin line to avoid unsmooth overflow after being laminated.
 3. The photo-curing process will not exhibit the phenomenon of air surging. When exposing to rear-section thermal curing, it presents higher curing reaction rate to meet the intensity requirements.
 4. Our products comply to the newest international environmental regulations, such as RoHS 2.0, Halogen Free, PFOA, PFOS and REACH, etc.
 5. The weather resistance of this resin are excellent, which can afford the conditions of -40°C*500hr, 85°C*500hr, -40°C~85°C*30 cycles, 85°C*85%RH*168hr.

Product Model :
JB093 Series Cationic epoxy resin



Adhesive Applied to Photosensitive Sensor Module Industry

Since optoelectronic technology multimedia products have more and more emphasized on multiple applications of photosensitive sensors for cameras, photography, barcode scanning, fingerprint scanner, face scanner, and so on biometric recognition. Every period of time, many new structure products will be developed. To meet the demand of the industry, Everwide develop and launch a series of adhesives, which are corresponding to the application required by a variety of module structure each three years. Driven by this, products have higher operability, higher level of environment test standard, more effective eco-friendly material control as well as higher efficiency and more cost-effective were born.

Nowadays, lens of modules are more and more widely used in electric vehicles, security monitoring systems in public places, aviation industry and aerospace, precision medical devices, and so on areas. Therefore, according to adhesion, the demand level for sealing-orientation materials are getting much higher, and also demand strict for environment protection that makes many chemical raw materials cannot be used. This situation makes every manufacture developers of the raw materials become troublesome, and try to ask for upper raw suppliers to develop eco-friendly materials to solve this problem.



Everwide has a foothold on Taiwan based on the plentiful raw materials support suppliers from Europe, America, South Korea, Taiwan, and so on. We can provide our customers with the most efficient solutions for various applications to make your product structure design more flexible. The Better regulations on environmental tests, and can gain best C/P value and technical service application materials. In this way, our customer can get the best application materials with the optimal cost performance and high technical services.



Developing blueprint for the bonding materials of photosensitive sensor module industry

Everwide began to develop and launch the PLCC and CLCC products of photo-curing resin since 2003. After that, Everwide invests a lot of human resources to develop brand new products to adapt every kinds of new application demands. The following points are the product developing blueprint of Everwide : to develop new products to meet the needs of various new applications for the structural assembly of higher-level sensing modules. The products development includes :

- Fast curing of photo-curing adhesive.
- Low shrinkage of photo-curing adhesive.
- Low shrinkage photo-curing and heat-curing cation epoxy resin.
- After photo-curing and then reheat-curing of hybrid epoxy.
- Low temperature 60°C~80°C heat-curing with low stress epoxy resin.
- Heat-curing epoxy resin with low separation after plasma treatment used for plastic fibers material.
- Black cation epoxy resin with photo-curing and heat-curing at 80°C.
- Special epoxy resin, which can be cured under UV light and fast cure at 60°C low temperature.

Here are the most important characteristics of the adhesive photosensitive sensor module industry that focus on :

- Adhesive formulations need to comply to high-level international environmental requirements, especially for lenses of medical devices, automotive industry, and aerospace industry applications.
- The curing process requires very low volatility of small molecules. After curing and make through environmental long-term aging, it still requires quite low volatility.
- Most of adhesive requires the packages of 10ml, 30ml, and 50ml size syringe, so the average of syringe and the requirement of no air bubbles are very strict.
- Under the same working environment, the resin requires stable operability and have high reproducibility.
- The resin requires very strict quality inspections, and if it is used in the transportation industry, it must be complied to IATF 16949 certificate.
- Common environmental test standard for communication product level is -40°C*240hr, 85°C*240hr, -40°C (30 min) ~ 85°C (30 min)*100 cycles, 85°C*85%RH*240hr.
- Common environmental test standard for transportation equipment level is -40°C*240hr, 125°C*240hr, -40°C(120 min) ~ 125°C(120 min)*100 cycles, 85°C*85%RH*1000hr. The 3% salt spray test*168hr.
- Comply to the international environmental protection regulations, such as RoHS 2.0, Halogen Free, PFOA, PFOS, REACH newest version. Special restricted substances such as IBOA, THFA, and so on restricted materials are forbidden.

Overview of application examples in major industries :

Photosensitive module : mobile phone, tablet, laptop, computer, etc.



Major clients : YTOT, Sunny, AOET, GSEO, Luxvision, Chicony, Sunwin, OFILM, OPPO

Medical device



Major clients : Wistron

Electric car, motorcycle, bicycle



Major clients : Tesla, Giant, Calin, Canon

Optical signal identification



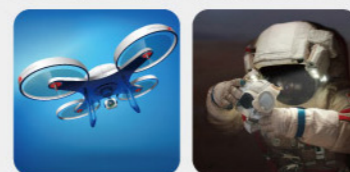
Major clients : Synaptics, Truly

Security monitoring devices



Major clients : D-Link

Aerial photography, space footage



Major clients : DJI, Parrot

R&D Capability, Quality Management System and Quality control capabilities certificate of Everwide :



ISO 9001 IATF 16949

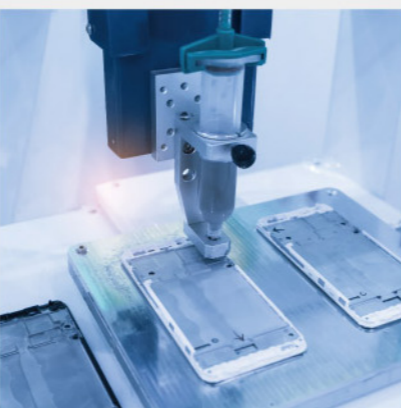


ISO 14001 ISO 45001



TTQS

Everwide product packaging :

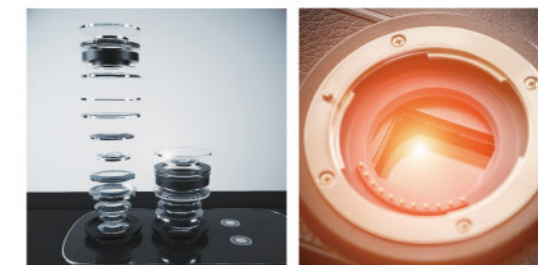


The successful product lines which lead in photosensitive sensor module industry :

Waterproof lens bonding applications in target lens industry

Product Feature :

1. Excellent bonding strength for the PC(GF), PA, LCP lens body and glass. For PC lens, which can achieve materials breaking and waterproof functions.
2. To co-operate with the efficiency factor for the production line, the dispense rate of resin is quite fast and the rate of curing after exposing to the light is also rapid.
3. Weather resistance of resin is excellent, which can afford the condition of -40°C*500hr, 100°C*500hr, -40°C~85°C*240 cycles, 85°C*85% RH*240hr.



Product Model :

- FP771 Series Photo-curing adhesive
- GN728 Series Photo-curing adhesive
- FR324 Series Photo-curing adhesive
- GN278 Series Photo-curing adhesive
- FR345 Series Photo-curing adhesive
- JD551 Series Low-temperature epoxy resin
- JE085 series Low-temperature epoxy resin



Bonding applications for the filter lens and lens holder

Product Feature :

1. Our products have excellent bonding strength for the PC(GF), PA, LCP lens and glass or PC lens, which can provide over 1kg of push pin thrust value.
2. Extruding rate of the resin is smooth and maintains a complete and straight resin line. The aspect ratio should be at least 0.7, which can effectively hold the lens mount.
3. Resin will maintain achieve certain balance level for the cohesion of the substrates, which can mitigate the impact during the dropping test.
4. The weather resistance of the resin is excellent, which can afford the conditions of -40°C*500hr, 100°C*500hr, -40°C~85°C*240 cycles, 85°C*85%RH*240hr.

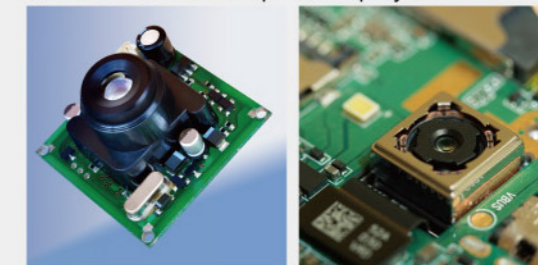
Bonding application of optics modules for the structural lens mount and circuit board

Product Feature :

1. Resin has excellent bonding strength for the PC (GF), PA, LCP lens holder and IR glass FR4 or FPC soft/ hard composite board to provide over 5 kg of thrust value.
2. Extruding rate of the resin is smooth and maintains a complete and straight resin line. The aspect ratio should be at least 0.7, which can effectively hold the lens mount.
3. Resin maintains certain level of balance for the cohesion between substrates and resin itself in order to mitigate the impact during the dropping test.
4. The weather resistance are excellent, which can afford conditions of -40°C*500hr, 100°C*500hr, -40°C~85°C*240 cycles, 85°C*85%RH*240hr.

Product Model :

- JE078 Series Low-temperature epoxy resin
- JE109 Series Low-temperature epoxy resin
- JE106 Series Low-temperature epoxy resin
- JD322 Series Low-temperature epoxy resin



Focus setting after inserting the lens into the lens mount—AF Thread Type

Product Feature :

1. The resin exhibits excellent bonding for PC(GF), PA, LCP lens mounts and plastic lenses with low-shrinkage stress.
2. The main body of resin is specially designed product with strong cohesion, which can be applied on rework applications.
3. The adhesive exhibits high viscosity and excellent anti-sagging properties. Further, it must be able to dispense smoothly and be suitable for the manufacturing process by using the injection adhesive valve.
4. Shorter pre-fixation time and the photo-curing energy should be less than 1000mj/cm². Further, it should be suitable for LED 365nm and 395nm equipments.
5. The weather resistance of the resin are excellent, which can afford conditions of -40°C*500hr, 120°C*500hr, -40°C~125°C*240 cycles, 85°C*85% RH*240hr, salt spray test 3%*240hr.

Product Model :

- GP424 Series Photo-curing adhesive
- FR503 Series Photo-curing adhesive
- FR448 Series Photo-curing adhesive



Bonding and Fixation : focus fixation after inserting lens into the lens mount—AF Thread-free Type

Product Feature :

1. The product should be provided with the integral package. The UV curing epoxy should be fixed in advance and followed with photo-curing and low-temperature heating epoxy resin.
2. Photo-curing resin cure rapidly and meets the requirement of low shrinkage below 3%. Furthermore, the photo-curing epoxy should has high viscosity, without sagging and penetration.
3. The adhesive exhibits high viscosity and excellent anti-sagging properties. Further, it must be able to dispense smoothly and be suitable for the manufacturing process using the injection adhesive valve.
4. Short pre-fixation time and the photo-curing energy should be less than 1000mj/cm². Further, it should be suitable for LED 365nm and 395nm equipments.
5. The resin has excellent weathering resistance, which can afford the conditions of -40°C*500hr, 120°C*500hr, -40°C~125°C*240 cycles and 85°C*85%RH*240hr, salt spray test 3% *240hr.

Product Model :

- FR395 series Photo-curing adhesive
- JD857 series UV curable epoxy resin

